

Mounting Option

.156 [3.96] Dia. Mounting Holes

Contact Detail

90 Degree Bend (Code 541 Contacts)

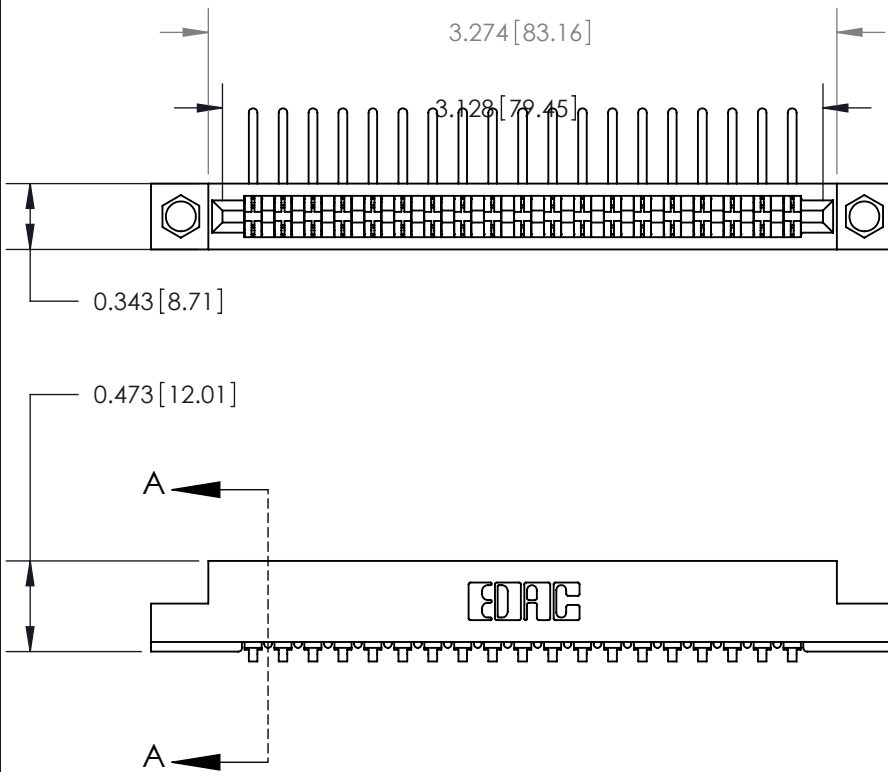
.156 [3.96] Contact Spacing x .200 [5.08] Row Spacing

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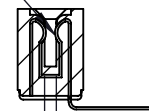


ISSUE NUMBER

ORIGINAL



.175 [4.45] Point of Contact
(Measured from bottom of Card Slot)



Card Slot Accepts .054 [1.37]
to .070 [1.78] Thick P.C. Board

SECTION A-A

See Accompanying Page for:

- Contact Bend Details

807/857 Series High Temp Card Edge Connector

Part Number: 807-019-557-104



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|-----------------------------------|------------------|
| ACAD REFERENCE NO. 807 ENG MASTER | |
| DRAWN: J.LEE | DATE: AUG. 11/09 |
| CHECKED: | DATE: |
| SCALE: NTS | SHEET 1 OF 2 |
| DRAWING NUMBER 807 Assembly | ISSUE 1 |

Single Row Contacts - Read One Side of Daughter Board

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ISSUE NUMBER
ORIGINAL



558 Contact Code



559 Contact Code

Single Row Contacts - Read Both Sides of Daughter Board



553 Contact Code



554 Contact Code



557 Contact Code

Dual Row Contacts - Read Both Sides of Daughter Board

0.240 [6.10] Up to 27/54 Pin
0.162 [4.11] 28/56 and Over



555 Contact Code



556 Contact Code



558 Contact Code



559 Contact Code



560 Contact Code

**807 Series High Temp Card Edge Connector
Contact Bend Detail**



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DRAWN: J.LEE DATE: AUG. 11/09

CHECKED: DATE:

SCALE: NTS SHEET 2 OF 2

DRAWING NUMBER ISSUE

807 Assembly

1